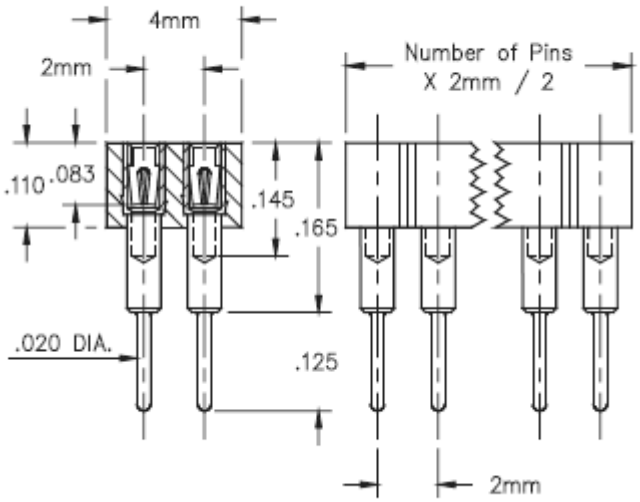
Product Number: 833-43-048-10-001000



Description:
Interconnect Socket
2mm Grid; Straight Socket
Double Row
Through Hole
Accepts .015-.025" Leads
Plating Code:
43
Shell Plating:
200 µ" Tin (matte finish) over 100 µ" Nickel
Inner Contact Plating:
30 µ" Gold over 50 µ" Nickel

# Of Pins	Mill-Max Part Number	RoHS Compliant
48	833-43-048-10-001000	RoHS 2002/95/EC

CONTACT:

Contact Used: #32, Low Force 6 Finger Contact
Current Rating = 3 Amps

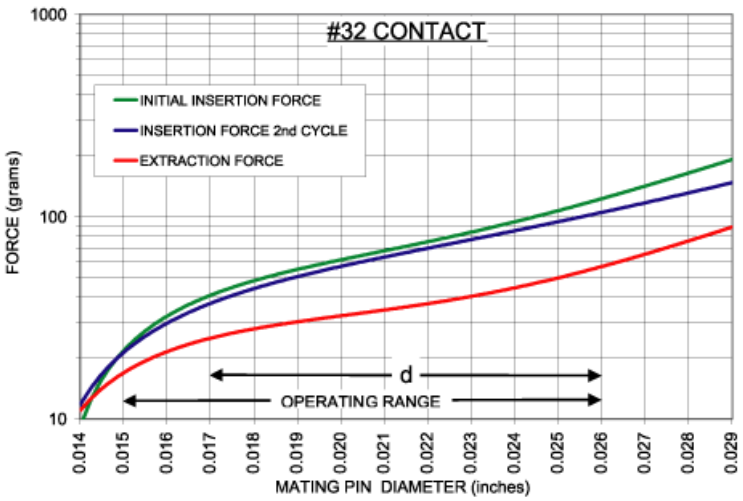
BERYLLIUM COPPER ALLOY 172 (UNS C17200) per ASTM B 194

Properties of BERYLLIUM COPPER:

- Chemical composition: Cu 98.1%, Be 1.9%
- Temper as stamped: TD01

Properties after heat treatment (TH01):

- Hardness: 36-43 Rockwell C
- Mechanical Life: 100 Cycles Min.
- Density: .298 lbs/in3
- Electrical Conductivity: 22% IACS*
- Resistance: 10 miliohms Max
- Operating Temperature: -55°C/+125°C
- Melting point: 980°C/865°C (liquidus/solidus)
- Stress Relaxation†: 96% of stress remains after 1,000 hours @ 100 ºC ; 70% of stress remains after 1,000 hours @ 200 ºC



*International Annealed Copper Standard, i.e. as a % of pure copper.

†Since BeCu loses its spring properties over time at high temperatures; it is rated for continuous use up to 150°C. For applications up to 300°C, Mill-Max offers many contacts in Beryllium Nickel. Contact Tech Support for more info.

LOOSE PIN:

Loose Pin Used: 1802

BRASS ALLOY (UNS C36000) per ASTM B 16

Properties of BRASS ALLOY:

- Chemical composition: Cu 61.5%, Zn 35.4%, Pb 3.1%†
- Hardness as machined: 80-90 Rockwell B
- Density: .307 lbs/in3
- Electrical conductivity: 26% IACS*
- Melting point: 900°C/885°C (liquidus/solidus)

†(3 to 4% lead is used to permit "free machining" and is permitted by EC Directive 2002/95Annex 6; so all pin materials are RoHS compliant)

*International Annealed Copper Standard, i.e. as a % of pure copper.

INSULATOR INFORMATION:

NYLON 46 (Stanyl TE250F6 {30% glass} or TE250F9 {45% glass}, black)

High Temperature

Properties of NYLON 46:

- Brand: Stanyl
- Grade: TE250-F6 or F9
- Material Heat Deflection Temp. (per ASTM D 648): 554°F (290°C) @ 264 psi

Note: Materials above 446°F (230°C) are considered suitable for "eutectic" reflow soldering, above 500°F (260°C) for "lead-free" reflow soldering.